

4218975/A 07/2015

PowerPAD is a trademark of Texas Instruments.

NOTES:

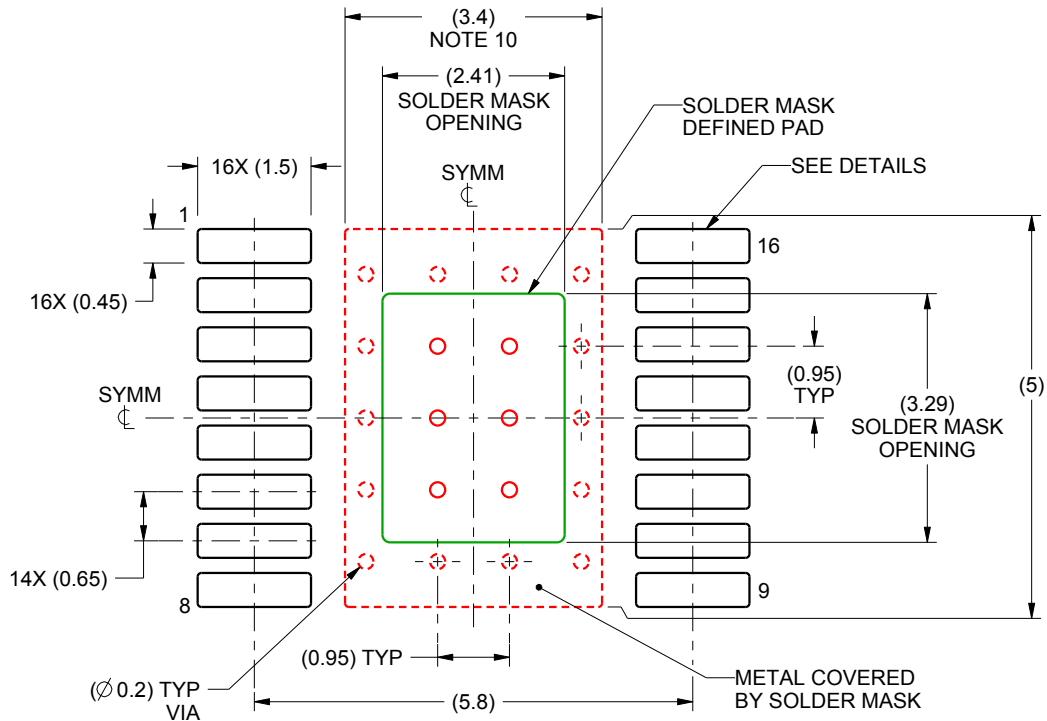
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.
6. Features may not be present.

EXAMPLE BOARD LAYOUT

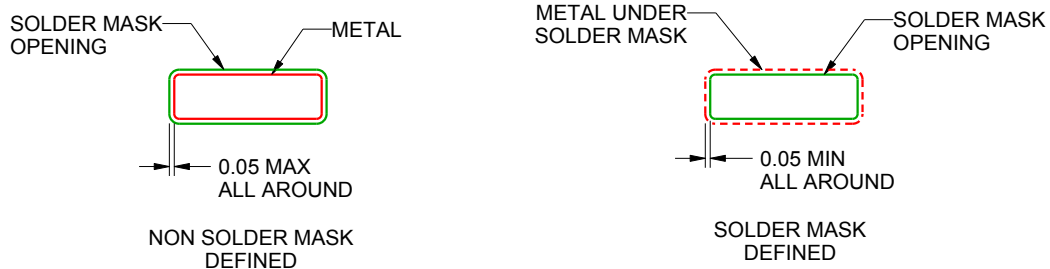
PWP0016G

PowerPAD™ - 1.2 mm max height

PLASTIC SMALL OUTLINE



LAND PATTERN EXAMPLE
SCALE:10X



SOLDER MASK DETAILS
PADS 1-16

4218975/A 07/2015

NOTES: (continued)

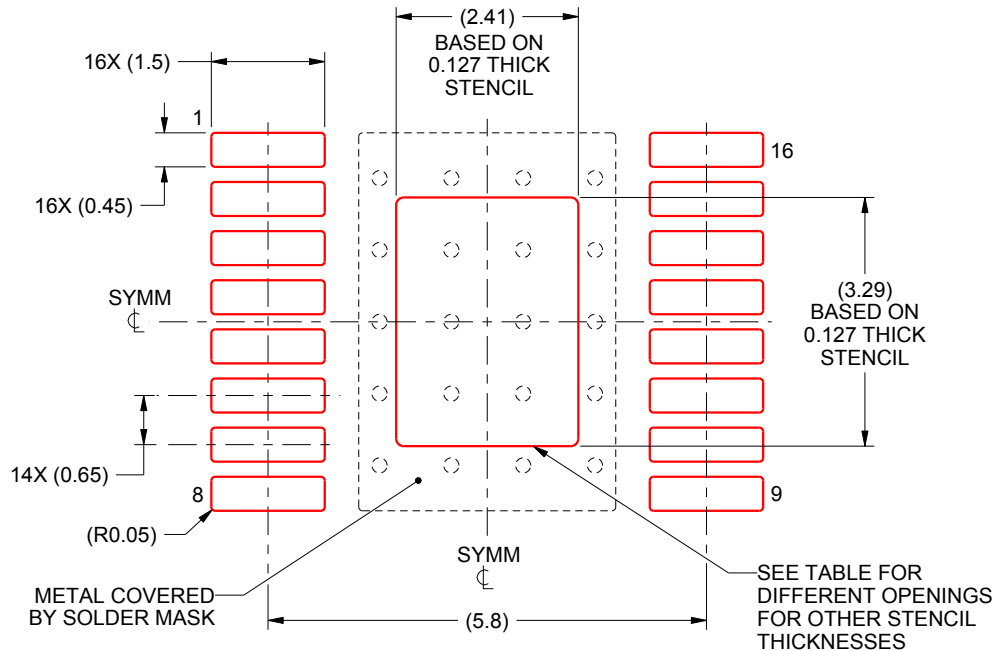
7. Publication IPC-7351 may have alternate designs.
8. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
9. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature numbers SLMA002 (www.ti.com/lit/slma002) and SLMA004 (www.ti.com/lit/slma004).
10. Size of metal pad may vary due to creepage requirement.

EXAMPLE STENCIL DESIGN

PWP0016G

PowerPAD™ - 1.2 mm max height

PLASTIC SMALL OUTLINE



SOLDER PASTE EXAMPLE
 EXPOSED PAD
 100% PRINTED SOLDER COVERAGE BY AREA
 SCALE:10X

STENCIL THICKNESS	SOLDER STENCIL OPENING
0.1	2.72 X 3.71
0.127	2.41 X 3.29 (SHOWN)
0.152	2.20 X 3.01
0.178	2.04 X 2.78

4218975/A 07/2015

NOTES: (continued)

11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.